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(54) **SUBSTRATE DEBONDING FROM BONDED PART**

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(57)

ABSTRACT

A method for debonding a bonded part includes attaching a handle to a third side of a first substrate of the bonded part with an adhesive layer. The bonded part has a plurality of inter-substrate bond structures that couple a first side of the first substrate to a second side of a second substrate. The third side of the first substrate is opposite the first side. The first substrate and the second substrate have different thicknesses. The method includes absorbing a solvent into the adhesive layer, swelling the adhesive layer in response to the absorbing of the solvent, bending the first substrate in response to the swelling, and breaking a plurality of thermocompression bonds between the plurality of inter-substrate bond structures and the second side of the second substrate in response to the bending to debond the first substrate.

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